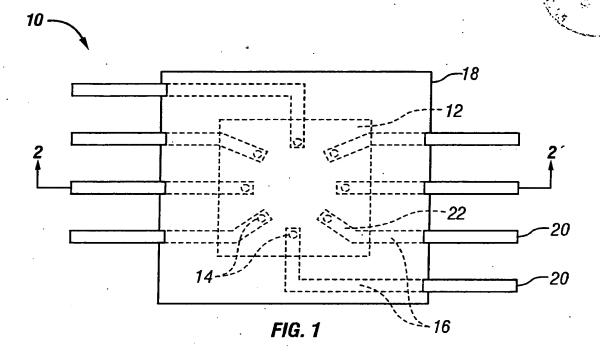
Flip chip-in-leadframe pack and process Title:

Inventor: PENDSE, et al. USSN: 09/802,443

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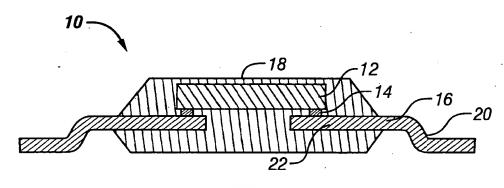
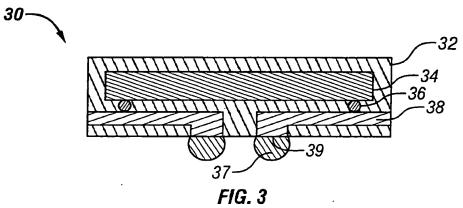


FIG. 2



Title: Flip chip-in-leadframe packs and process

Inventor: PENDSÉ, et al. USSN: 09/802,443



